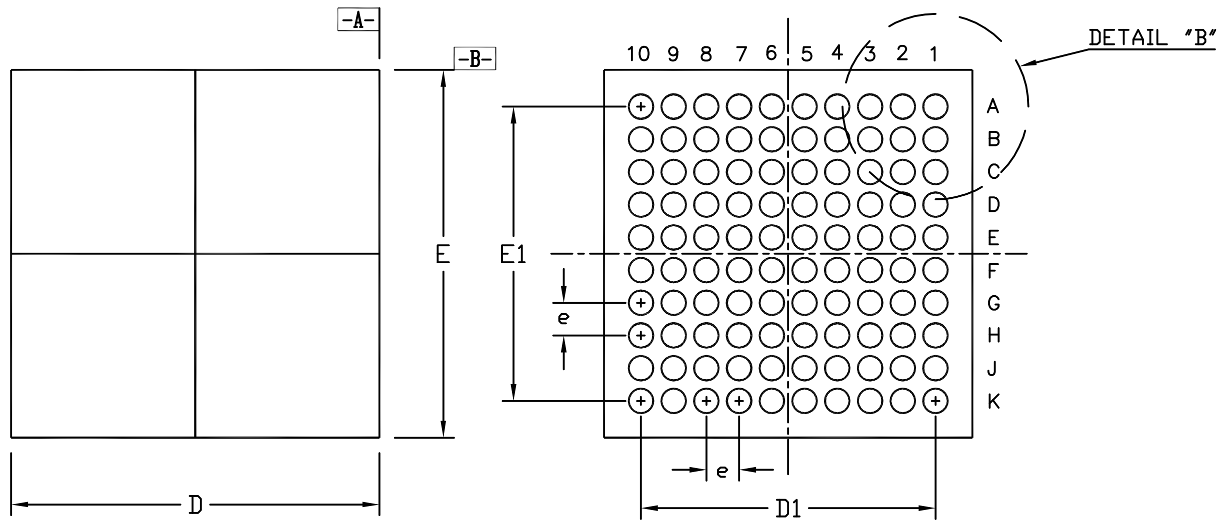

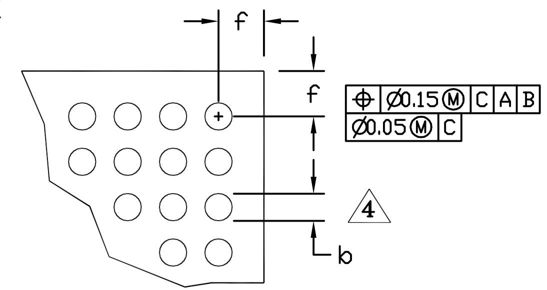

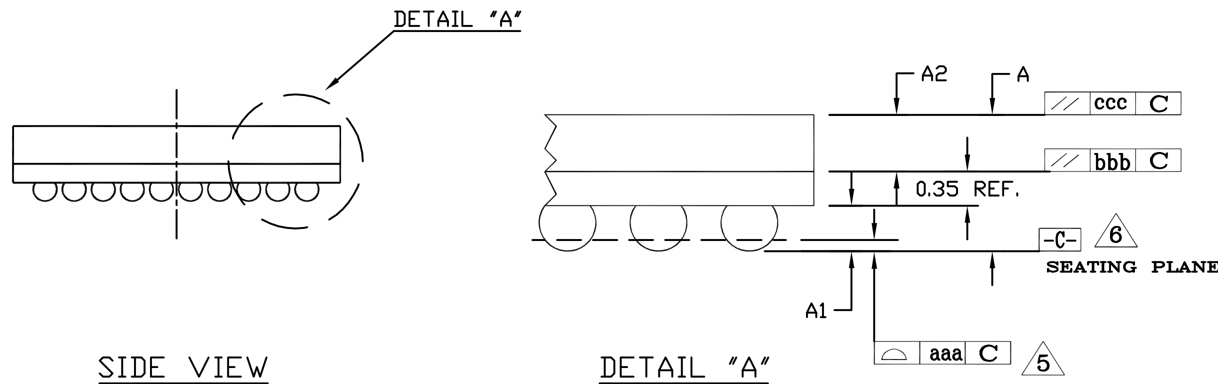

DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
A	1.25	1.40	1.50
A1	0.35	0.40	0.45
A2	0.55	0.65	0.75
D	8.90	9.00	9.10
D1	7.20 BSC		
E	8.90	9.00	9.10
E1	7.20 BSC		
b	0.45	0.50	0.55
aaa	--	--	0.12
bbb	--	--	0.10
ccc	--	--	0.10
e	0.80 BSC		
f	0.80	0.90	1.00
M	10		
N	100		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. 'e' REPRESENTS THE BASIC SOLDER BALL GRID PITCH.
3. 'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE. AND SYMBOL 'N' IS THE NUMBER OF BALLS AFTER DEPOPULATING.
4. 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER AFTER REFLOW PARALLEL TO PRIMARY DATUM -C- .
5. DIMENSION 'aaa' IS MEASURED PARALLEL TO PRIMARY DATUM -C- .
6. PRIMARY DATUM -C- AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
7. PACKAGE SURFACE SHALL BE MATTE FINISH.
8. SUBSTRATE MATERIAL BASE IS BT RESIN.
9. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
10. DRAWINGS CONFORMS TO JEDEC MO205 LATEST REVISION.

DALLAS SEMICONDUCTOR MAXIM

PROPRIETARY INFORMATION

TITLE: PACKAGE OUTLINE, 100L CSBGA, 9x9x1.4mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
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